



# **The Future of PCI Express® Architecture**

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**Chair, PCI Express Steering Committee**



# What They're Saying...

## WIKIPEDIA

### Outlook (2005)

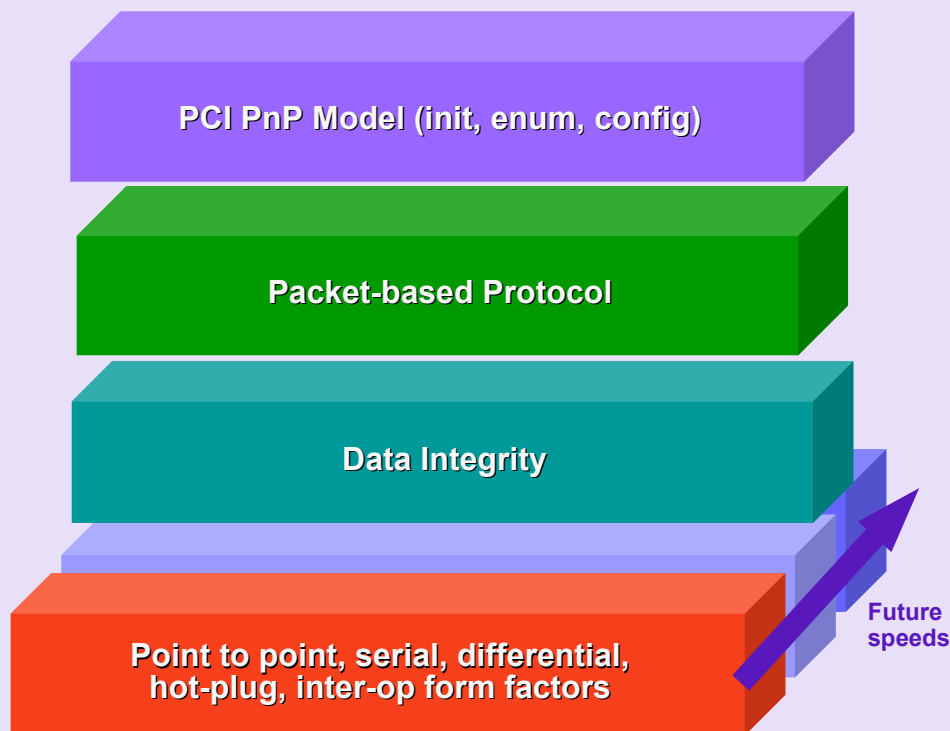
PCI Express appears to be well on its way to becoming the new backplane standard in personal computers ... the principal reason is that it was designed to be **completely transparent to software developers** - an operating system designed for PCI can boot in a PCI Express system without any code modification. Other secondary reasons include its **enhanced performance** and **strong brand recognition**.

Most of the new **graphics** cards use PCI Express ... Most new **Gigabit Ethernet** chips and some **802.11 wireless** chips also use PCI Express ... Other hardware such as **RAID controllers** and **network cards** are also starting to make the switch ... hence supplanting the AGP and PCI-X® connectivity ... ExpressCard\* is just starting to emerge on laptops.

# Agenda

- **PCI Express 2.0 Overview**
- The Future of PCI Express Architecture
- Call to Action

# PCIe® 2.0 Snapshot



## ■ Software & Protocols

- ✓ Completion timeout
- ✓ Function-level reset
- ✓ Access control services
- ✓ Link bandwidth notification
- ✓ Link speed controls

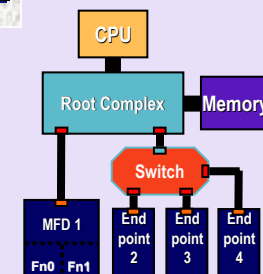
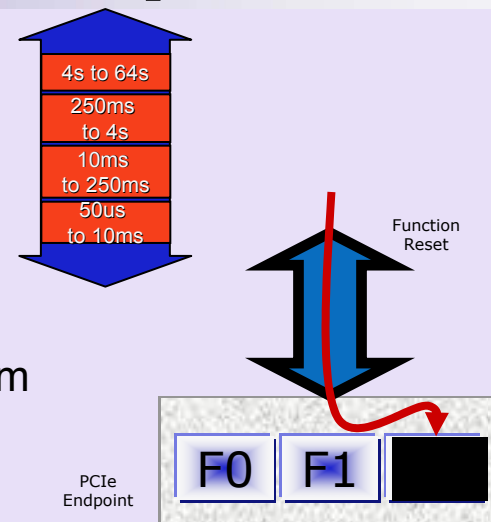
## ■ Physical

- ✓ 5GT/s signaling
- ✓ Speed negotiation
- ✓ Dynamic link reconfiguration
- ✓ Margining and compliance

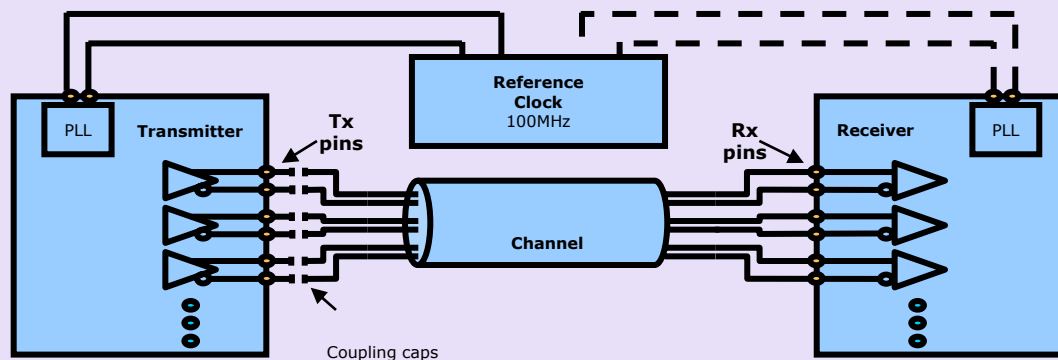
**Enhancements to the protocol layer**  
**Significant changes to the PHY layer**

# PCIe 2.0 Protocol Updates

- **Completion Timeout**
  - ✓ Required disable mechanism
  - ✓ Optional programmability
- **Function Level Reset (FLR)**
  - ✓ Optional enhanced software reset mechanism
  - ✓ Supports improved robustness, virtualization
- **Access Control Services (ACS)**
  - ✓ Enhanced control/robustness for peer to peer traffic
  - ✓ Supports virtualization
- **Link Bandwidth Notification Mechanism**
  - ✓ Software notification of link speed/width changes
- **Link Speed Control**
  - ✓ Protocol changes to match the Physical Layer



# PCIe 2.0 Electrical Updates



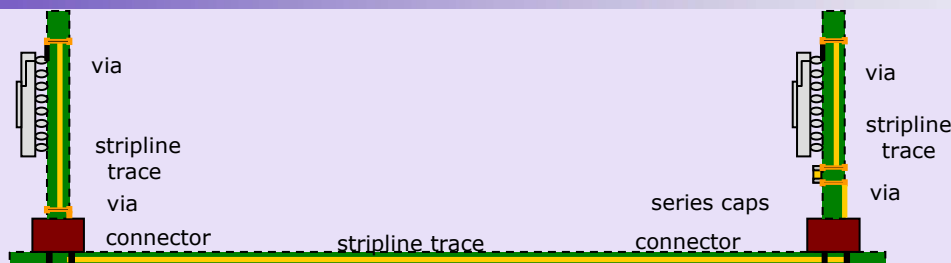
- **All interconnect components specified for interoperability**
  - ✓ PCIe 1.0a: Transmitter
  - ✓ PCIe 1.1: PCIe 1.0a + Reference Clock
  - ✓ PCIe 2.0: PCIe 1.1 + Channel + Receiver
  
- **Evaluating selectable Tx de-emphasis: -3.5 and -6 dB**
  - ✓ Design flexibility for short (reflective) and long (lossy) channels
  
- **Tx margining: for high-speed interconnect reliability**
  - ✓ Supports wide dynamic voltage range (max 1.2V, min 0.8V) to drive system into failure

**Design and validate all parameters to the limit of the allowed budgets**

# PCIe 2.0 LTSSM Updates

- **Speed Negotiation**
  - ✓ Dynamic link speed adjustment
  - ✓ Improves RAS and power savings
- **Compliance Speed**
  - ✓ In-band and programmable compliance pattern speed
  - ✓ Flexibility and reduced cost to implement compliance testing
- **Electrical Idle Entry/Exit**
  - ✓ Protocol enhancements to facilitate circuit design
  - ✓ Improves RAS, yield and ease of design
- **Link Width Reconfiguration**
  - ✓ Increase link width to original trained width
  - ✓ Improves power savings
- **Compliance Entry/Exit**
  - ✓ Device configuration despite failures
  - ✓ Improves RAS

# PCIe 2.0 Cards/Slots

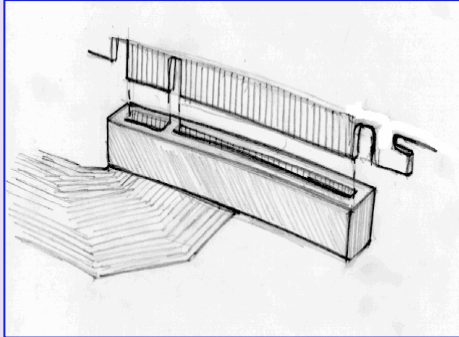


- **High-volume design guidelines and considerations**
- **Simulation modeling in progress for various topologies**
  - ✓ Impedance targets
  - ✓ Trace lengths
  - ✓ Connectors
- **Evaluating behavioral variations for optimum solution space**
  - ✓ Data pattern
  - ✓ De-emphasis settings: -3.5 or -6 dB
  - ✓ 85Ω PCB impedance target
  - ✓ 1pf package model

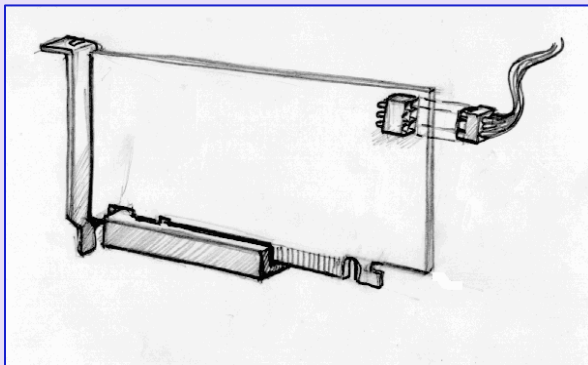
**Focus: Interoperability by construction**



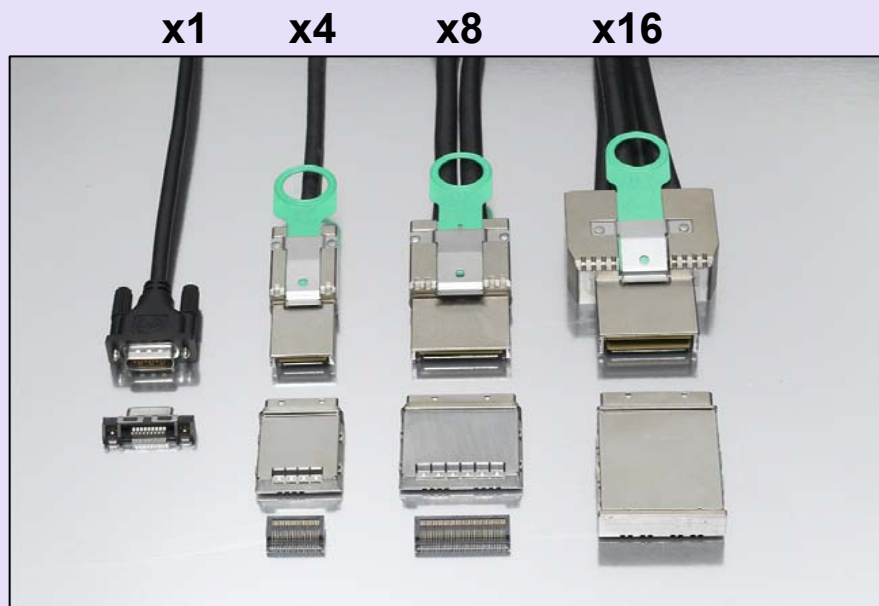
# Graphics Updates



- **Slot short-wiring (a.k.a. downshifting) to enable dual-graphics and other applications**
  - ✓ Interim (CEM 1.1): short-wired slot
  - ✓ Long-term (CEM 2.0): downshifted ports
  
- **225W/300W specification for high-end discrete graphics (ATX)**
  - ✓ Comprehends thermals/cooling/air flow
  - ✓ Power delivered via new 2x4 connector



# Other Form Factors



*Picture courtesy of Molex*

- Cable specification is at draft 0.7 revision
  - ✓ Decoupled from 5G signaling
  - ✓ Cable assemblies have been measured and validated
  - ✓ x16 Connector pin-out has changed
  
- Moving to draft 0.9 in 3Q06
  - ✓ Prove worst-case budgets meet PCIe 1.1 signaling requirements

# Looking Ahead



3Q06

4Q06

**PCIe Base 2.0  
v0.9 to BoD**

**PCIe CEM 2.0  
v0.5 to BoD**

**PCIe Base 2.0  
v0.9 to PCI-SIG**

**PCIe CEM 2.0  
v0.5 to PCI-SIG**

**PCIe CEM 2.0  
v0.9 to PCI-SIG**

**IOV v0.9 to  
PCI-SIG**

**PCI-SIG member collaboration needed for 2007-2008 product ramp**

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# Factors Driving PCIe Futures

## ■ Multi-Everything!

- ✓ CPUs, multi-core, operating systems
- ✓ Device virtualization and sharing
- ✓ Multiple graphics cards

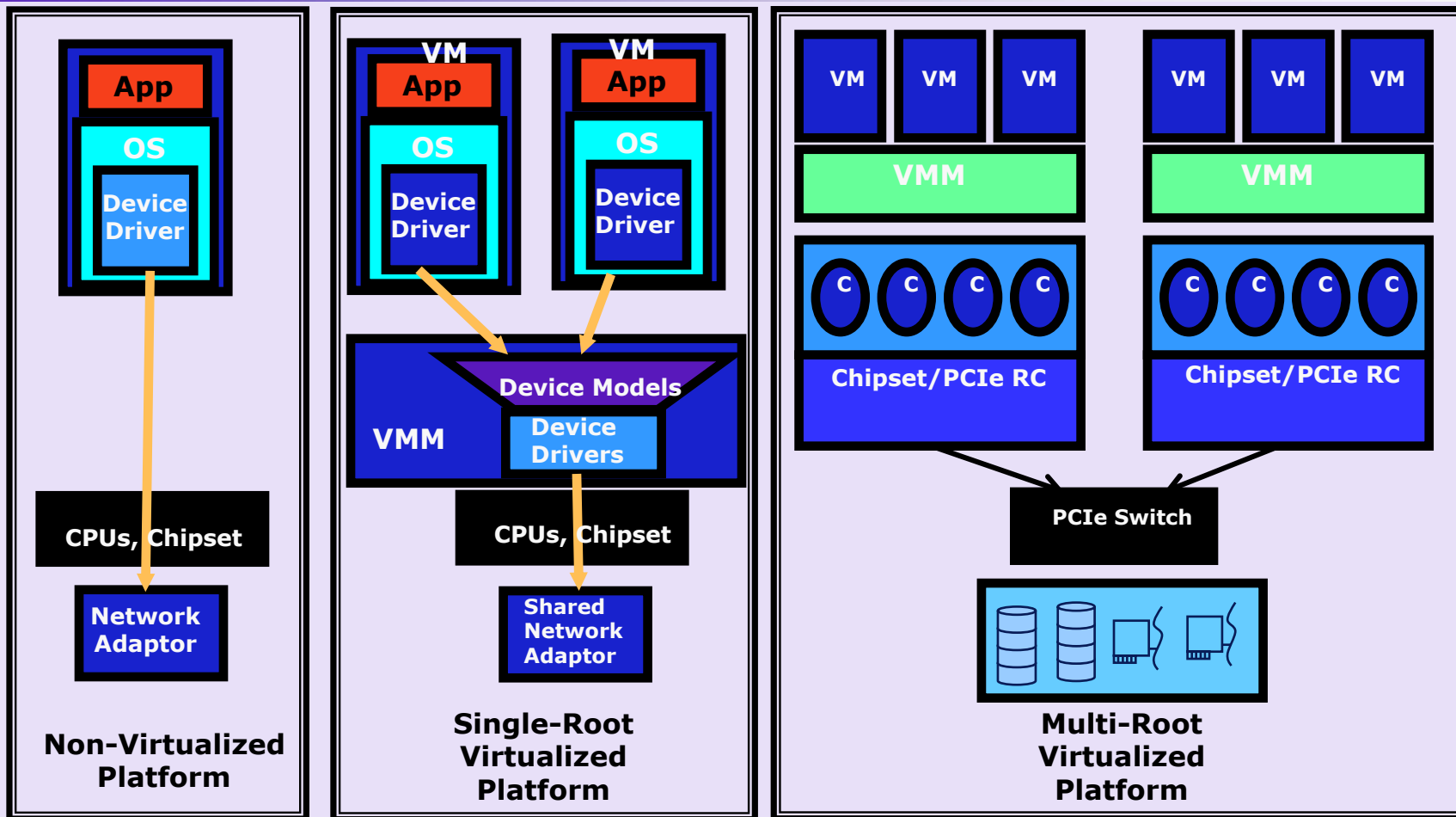
## ■ Higher Performance

- ✓ Next generation graphics, storage, networking and fabrics
- ✓ Need for more connectivity: flexible interconnect width/speed
- ✓ Lower power

## ■ Technology advances

- ✓ Si process
- ✓ High volume manufacturing
- ✓ Materials

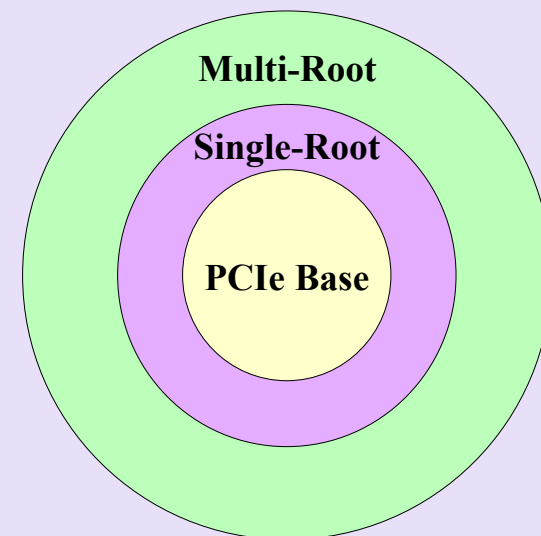
# I/O Virtualization Extensions



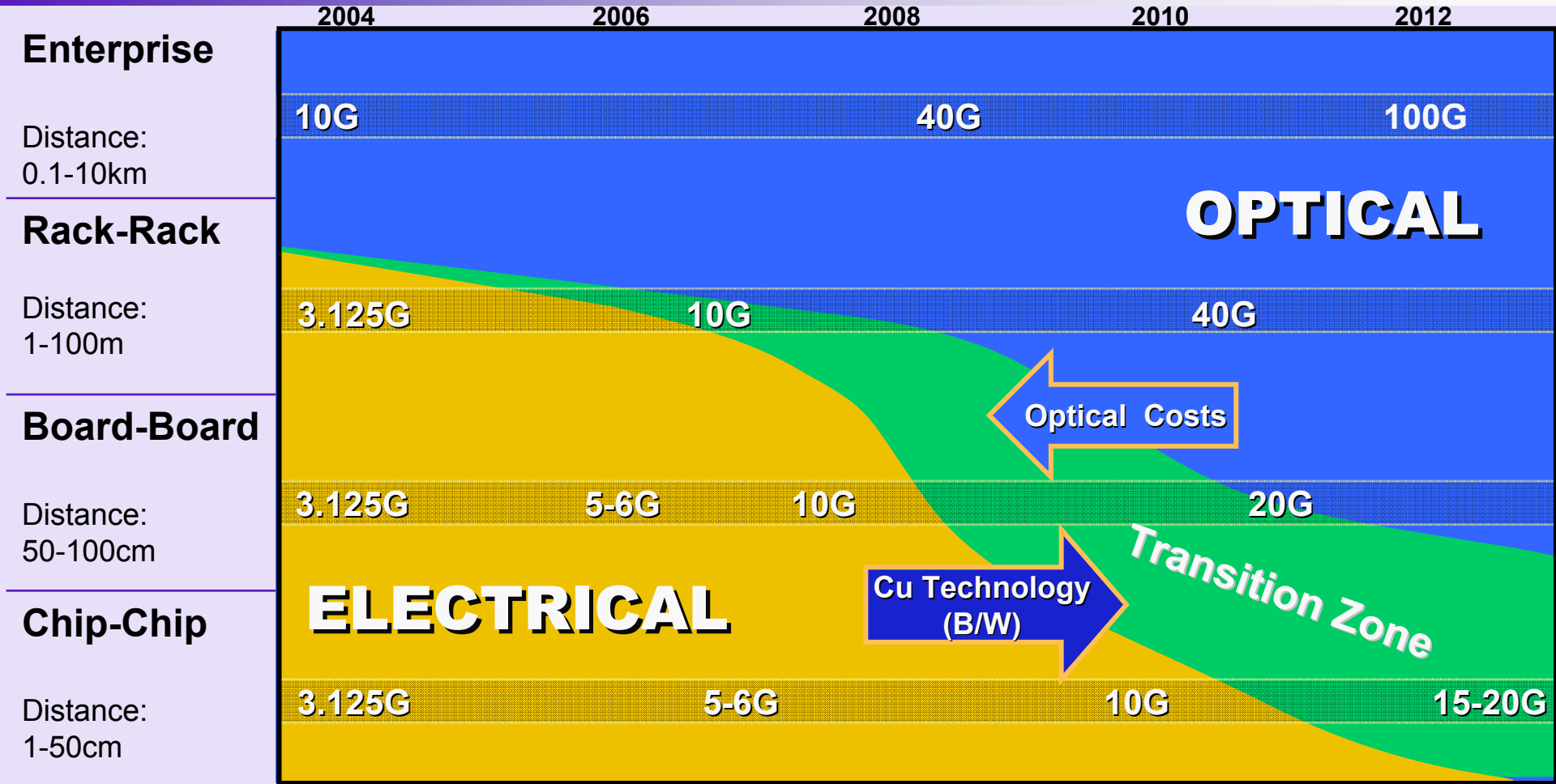
**PCIe enables efficient virtualization of I/O devices**

# IOV Technical Approach

- **Limited to PCIe specification suite**
  - ✓ Base, PCIe Bridge, etc.
- **Enables endpoints to be shared by guest operating systems**
  - ✓ Single- and multi-root scenarios
  - ✓ Create, manage, remove virtual resources
- **Compatibility**
  - ✓ New IOV capabilities defined as supersets of PCIe specifications
  - ✓ Limited functionality with existing software
  - ✓ Software intermediary owns configuration space
- **Control of inter-domain peer-to-peer**
- **Endpoint caching of address translations**



# Interconnect Speeds



**Cu is the incumbent technology**



# Future PCIe Specifications

- **Compatibility**
  - ✓ Interoperability with previous generations
- **Performance Target**
  - ✓ ~2x increase over PCIe 2.0 data rate
- **Cost**
  - ✓ High-volume manufacturing considerations
- **Architectural Enhancements**
  - ✓ I/O device virtualization
  - ✓ Form factor innovations
- **Schedule**
  - ✓ Driven by market requirements

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# Call to Action

- Immerse yourself in the PCI Express architecture training at this Conference!
- Innovate and differentiate your products with PCI Express 2.0 technology
- Contribute to the evolution of PCI Express architecture
- Visit [www.pcisig.com](http://www.pcisig.com) for specification updates

# PCIe 2.0 @ DevCon

Day 1

Track 1 - PCI Express

8:30am - 9:00am	Keynote	The Future of PCI Express Architecture <i>Ajay Bhatt</i>
9:00am - 10:00am	Session 1	<b>PCIe 2.0 Phy Architecture</b> <i>Debendra Das Sharma</i>
10:00am - 11:00am	Session 2	<b>PCIe 2.0 Electricals Tutorial - Part 1</b> <i>Jeff Morriss, Gerry Talbot</i>
11:00am - 12:00pm	Session 3	<b>PCIe 2.0 Electricals Tutorial - Part 2</b> <i>Jeff Morriss, Gerry Talbot</i>
12:00pm - 1:30pm	Exhibit Area	Lunch and Exhibit
1:30pm - 2:30pm	Session 4	<b>PCIe 2.0 Cards/Slots</b> <i>Dan Froelich</i>
2:30pm - 3:30pm	Session 5	<b>PCIe 2.0 Protocol Updates</b> <i>Joe Cowan</i>
3:30pm - 4:00pm	Exhibit Area	
4:00pm - 5:00pm	Session 6	Mobile Form Factor Updates <i>Ron Shaw</i>

**For other tracks and sessions, refer to the full conference schedule**

Thank you for attending the  
PCI-SIG Developers Conference 2006.

For more information please go to  
[www.pcisig.com](http://www.pcisig.com)